DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

TRANSPARENT CONDUCTIVE MULTI-LAYER STRUCTURE,							
PROCESS FOR ITS MANUFACTURE AND DEVICE MAKING USE OF							
TRANSPARENT CONDUCTIVE MULTI-LAYER STRUCTURE							
the specification	on of which is attached hereto u	nless the following is ch	ecked				
was filed on as United States Application Number or was filed on OCTOBER 22, 2004 as PCT							
International Application Number PCT/JP2004/016054 and was amended on (if applicable).							
I hereby state to claim(s), as an	that I have reviewed and undersonended by any amendment refer	and the contents of the a red above.	bove-identified specification,	including the			
I acknowledge Regulations, §	the duty to disclose information 1.56.	which is material to pa	tentability as defined in Title	37, Code of Federal			
for patent or ir	foreign priority benefits under aventor's certificate listed below	and have also identified	below any foreign applicatio	n for patent or			
inventor's cert	ificate having a filing date before	e that of the application	for which priority is claimed.				
(List prior foreign applications. See note A)				Priority Claimed			
	366835/2003 (Number)	JAPAN (Country)	28/10/2003	Yes □ No			
	(Number)	(Country)	(Day/Month/Year Filed)				
	(N)	(C		☐ Yes ☐ No			
	(Number)	(Country)	(Day/Month/Year Filed)				
				☐ Yes ☐ No			
	(Number)	(Country)	(Day/Month/Year Filed)				
		•		Пу Пх.			
	(Number)	(Country)	(Day/Month/Year Filed)	☐ Yes ☐ No			
(See note B)	See attached list for	additional prior foreign					
insofar as the s in the manner information wh	the benefit under Title 35, Unit subject matter of each of the clai provided by the first paragraph nich is material to patentability een the filing date of the price	ms of this application is of Title 35, United State as defined in Title 37, C	not disclosed in the prior Uni s Code, § 112, I acknowledg ode of Federal Regulations,	ted States application e the duty to disclose § 1.56 which became			
41			State	us			
(List prior U.S. Applications)	(Application Serial No.)	(Filing Date)	Patented Pend	ing			
	(Application Serial 140.)	(riing Date)					
	-		Patented Pend	ing Abandoned			
	(Application Serial No.)	(Filing Date)					
			☐ Patented ☐ Pend	ing Abandoned			
	(Application Serial No.)	(Filing Date)		-			

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

23850

Please direct all communications to the following address:

23850 PATENT TRADEMARK OFFICE

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, ' 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(See note C)	Full name of sole or first inventor (given name, family name)		Masaya YUKINOBU			
	Inventor's signature	Masaya Likinoli	Date Mar. 22, 2006			
	Residence	Chiba, Japan	Citizenship Japanese			
	Post Office Address	c/o Ichikawa Research Laboratory,				
		SUMITOMO METAL MINING CO.,	, LTD.			
	3-18-5, Nakakokubun, Ichikawa-shi, Chiba 272-8588 Japan					
	Full name of second inventor (given name, family name)					
	Inventor's signature		Date			
	Residence		Citizenship			
	Post Office Address					
	Full name of third inv	rentor (given name, family name)				
	Inventor's signature		Date			
	Residence		Citizenship			
	Post Office Address					
•	Full name of fourth inventor (given name, family name)					
	Inventor's signature	version (given name, raining name)	Date			
	Residence		Citizenship			
	Post Office Address					
	Full name of fifth inventor (given name, family name)					
	Inventor's signature	emor (given name, family name)	Date			
•	Residence		Citizenship			
	Post Office Address		•			

NOTES

- A. Please list all foreign applications relating to the invention and check block, "yes" or "no".
- B. If more than 4 prior foreign applications, please check this box and attach a sheet listing the remaining prior foreign applications.
- C. For residence in the U.S., indicate <u>city and state</u>, for residence outside the U.S., indicate <u>city and country</u>. The "Post Office Address" must be an address acceptable by a Post Office for delivery of mail.